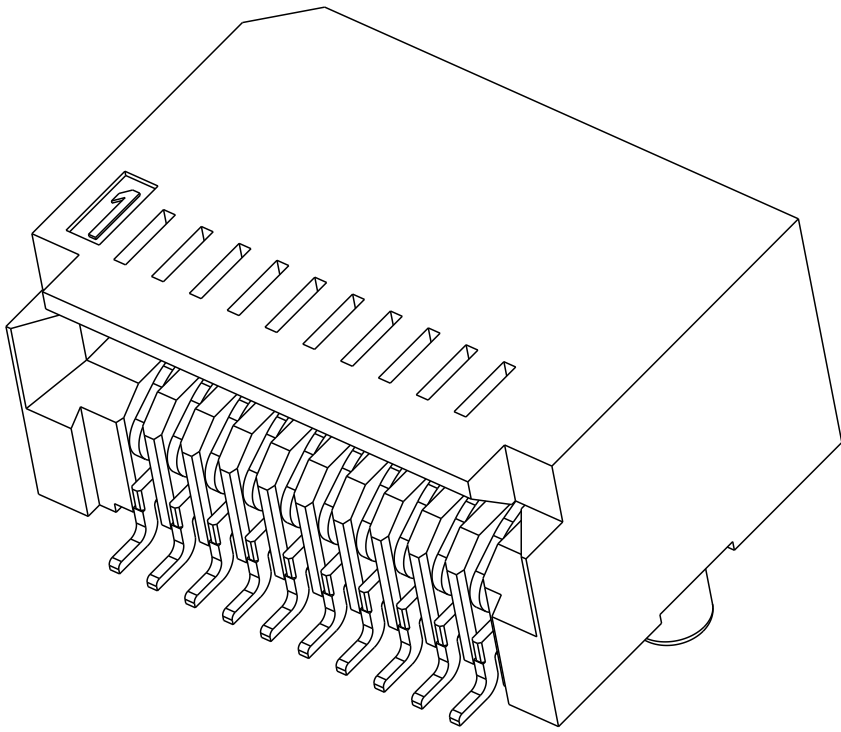


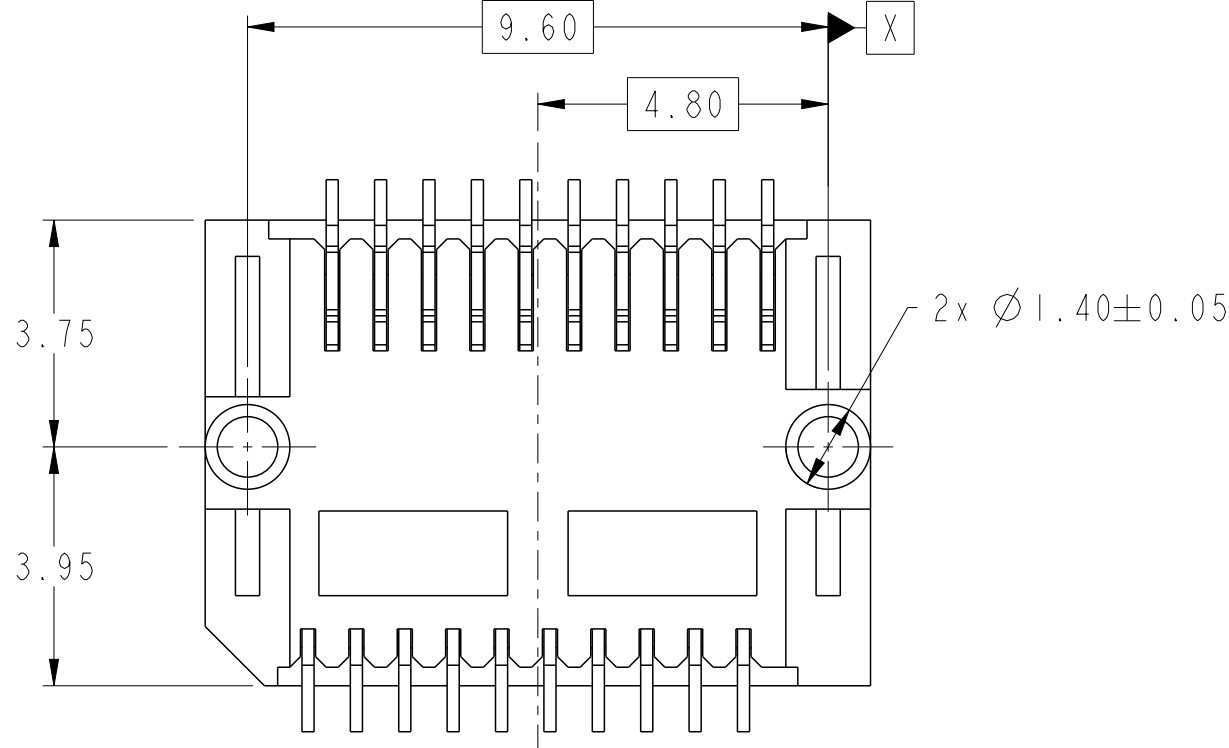
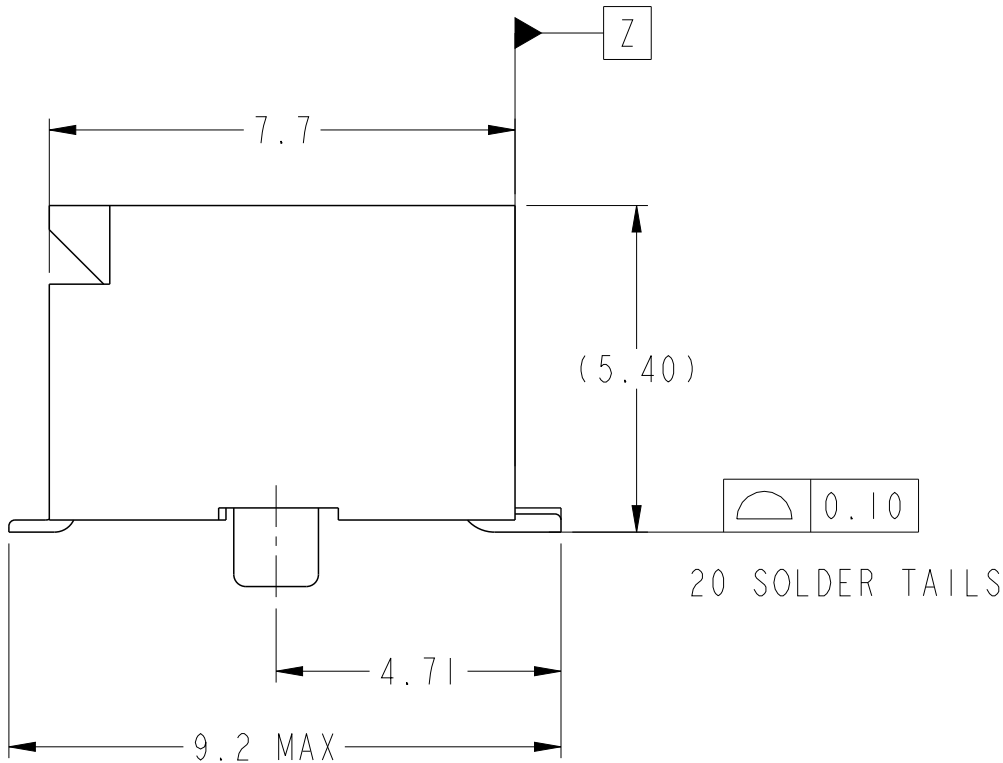
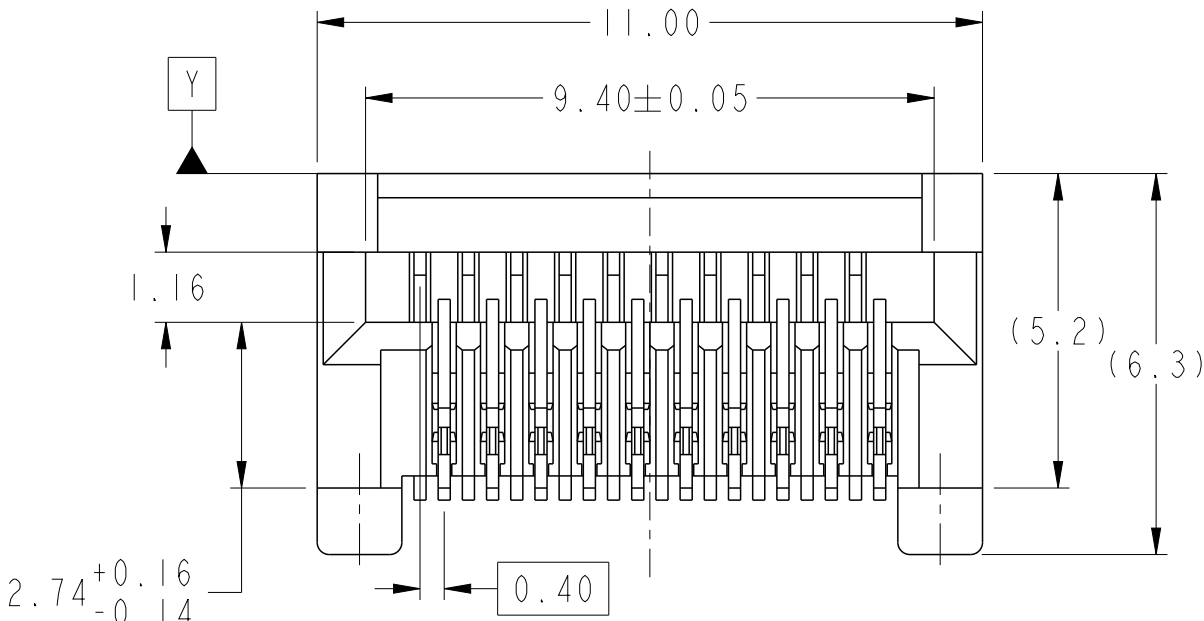
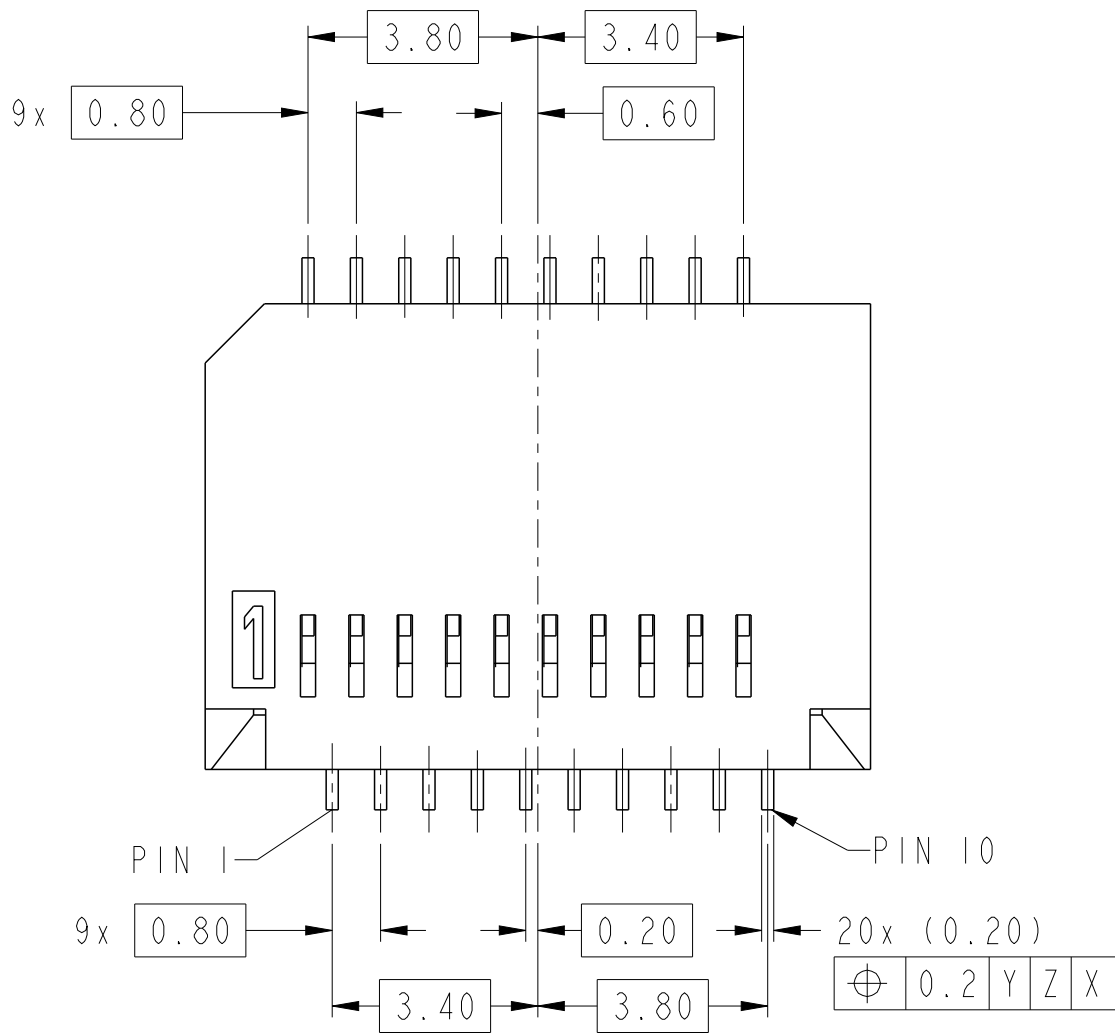
PRODUCT NUMBER	CONTACT AREA PLATING	PACKAGING
10122424-101LF	0.76µm Au	TAPE & REEL
10122424-901LF	0.38µm GXT	TAPE & REEL

NOTES:

1. MATERIAL:
HOUSING: HIGH PERFORMANCE RESINS,BLACK.
CONTACT: COPPER ALLOY.
2. PLATING:
UNDERPLATE: 1.27µm MIN NICKEL OVER ALL
SOLDER AREA: 2.54µm MIN TIN(LEAD FREE)
MATING AREA: SEE PRODUCT NUMBER TABLE.
3. DESIGNED TO CONFORM WITH SFP+ MSA SPECIFICATION.
4. PRODUCT SPECIFICATION: GS-12-1141
5. APPLICATION SPECIFICATION: GS-20-0385.
6. PACKAGE SPECIFICATION: GS-14-1399
7. PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND
OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.



3D VIEW
SCALE 8:1



spec ref	-	dr	Zhen Luo	2013/09/30	projection	MM	size	A2	scale	1:1
tolerance std	ISO 406 ISO 1101	eng	Art Lin	2014/05/27	chr	-	ecn no	ELX-DG-17776-1	rel level	Released
surface	ISO 1302	appr	Pei-Ming Zheng	2014/05/29	product family	-	cat. no.	-	Product - Customer Drw	sheet 1 of 2
linear	0.X ±0.25 0.XX ±0.15 0.XXX ±0.05	angular	0° ±2°	www.fci.com	title	SFP+ BOARD CONNECTOR SMT TYPE	dwg no	10122424	rev	C



PDS: Rev :C

STATUS: Released

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